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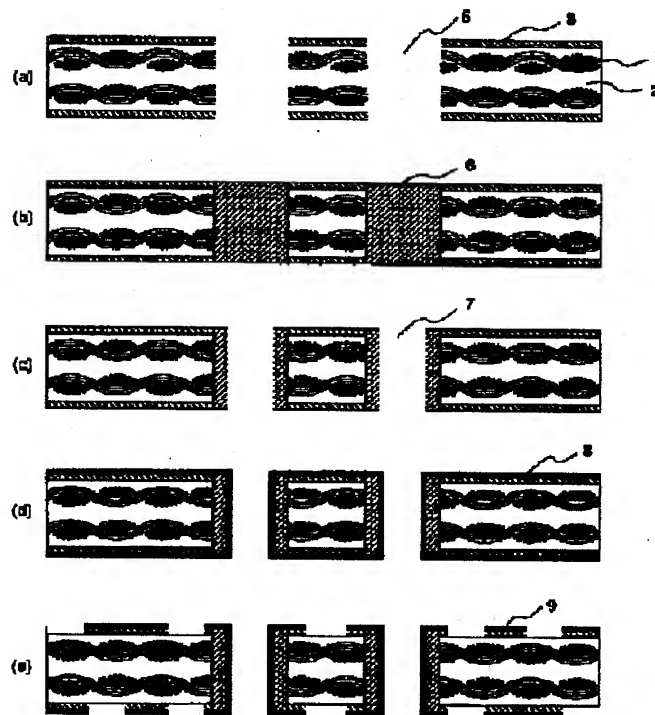
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APPLICANT : HITACHI LTD;

INVENTOR : YAMAGUCHI MOTOO;

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TITLE : PRINTED CIRCUIT BOARD AND ITS
MANUFACTURE



ABSTRACT : PROBLEM TO BE SOLVED: To eliminate migration in the case of exposure of fiber base material with an inner wall surface of a through hole by forming an insulation resin layer different from resin of a resin insulation base material of a printed circuit board between conductor metal of the hole and the base material of the board.

SOLUTION: A hole is opened at a copper-clad laminate made of glass woven fabric epoxy resin. And, filling resin 6 of phenol novolac type epoxy resin, bisphenol A type epoxy resin and imidazole curing agent is filled in the hole 5 and cured. And, after a through hole 7 is formed at a center of the resin 6, it is electrolessly copper plated, and then copper sulfate plated to form a plating layer 8. Then, etching resist pattern is formed, and an outer layer wiring 9 is formed by etching. Thus, the base material is not soaked with the metal, and no migration occurs.

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